To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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   Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSB226YP

Silicon Schottky Barrier Diode

ADE-208-842 (Z)

Rev. 0
Mar. 2000

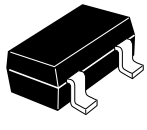
Features

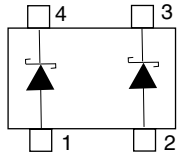
- Low reverse current, Low capacitance.
- CMPAK-4 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSB226YP	E5	CMPAK-4

Pin Arrangement





(Top View)

1 Anode
2 Anode
3 Cathode
4 Cathode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-Repetitive peak forward surge current	I_{FSM} [*1*2]	200	mA
forward current	I_F [*2]	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. 10msec sine wave 1 pulse

Notes: 2. Two device total

Electrical Characteristics [*1]

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	–	–	0.33	V	I_F = 1 mA
	V_{F2}	–	–	0.38	V	I_F = 5 mA
Reverse current	I_R	–	–	0.45	µA	V_R = 20V
Capacitance	C	–	–	2.80	pF	V_R = 1V, f = 1 MHz

Note: 1. Per one device

Main Characteristic

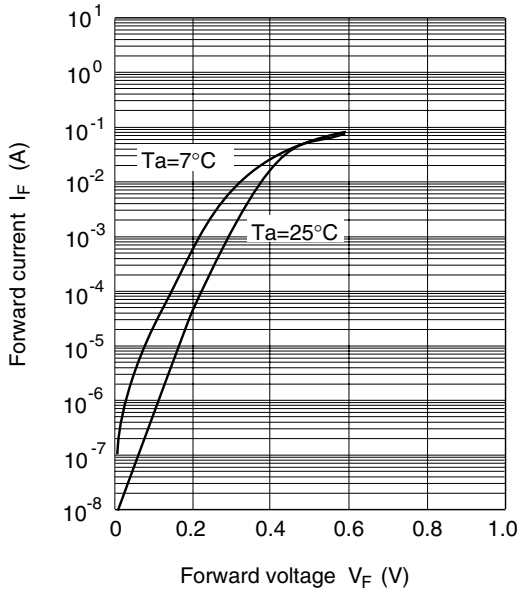


Fig.1 Forward current Vs. Forward voltage

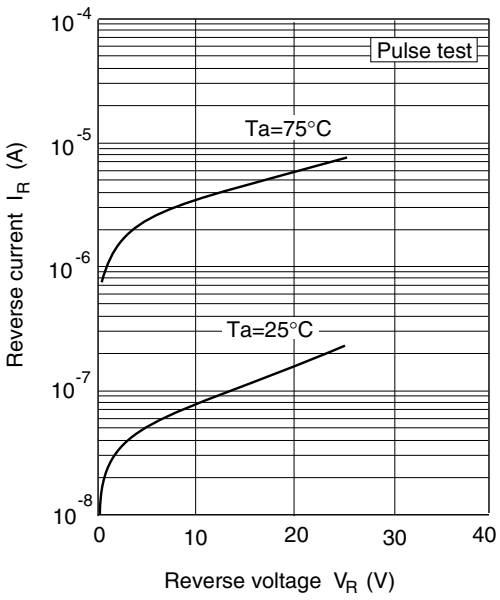


Fig.2 Reverse current Vs. Reverse voltage

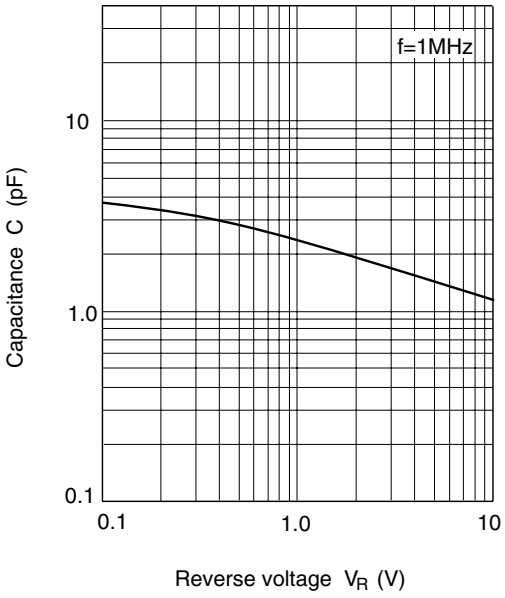
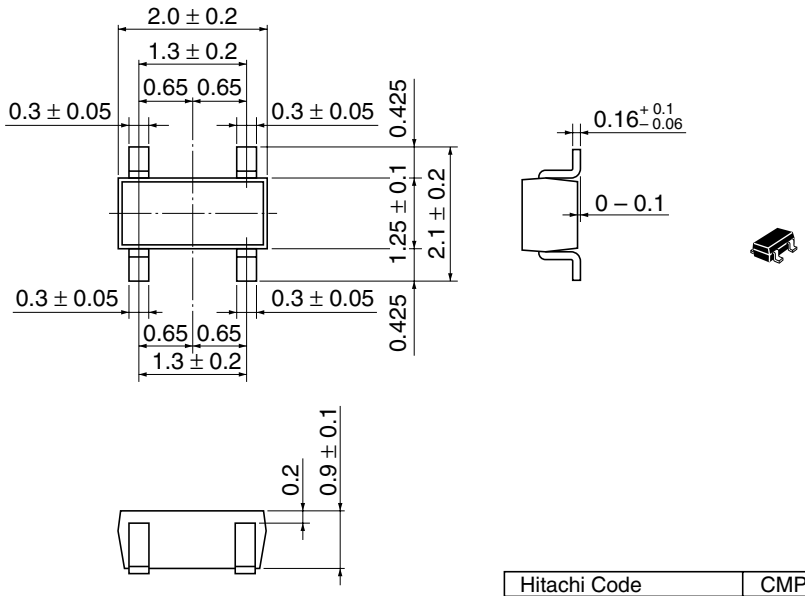


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	CMPAK-4
JEDEC	—
EIAJ	Conforms
Mass	0.006 g

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